

Crystal LTD TM SPEC Form

Customer

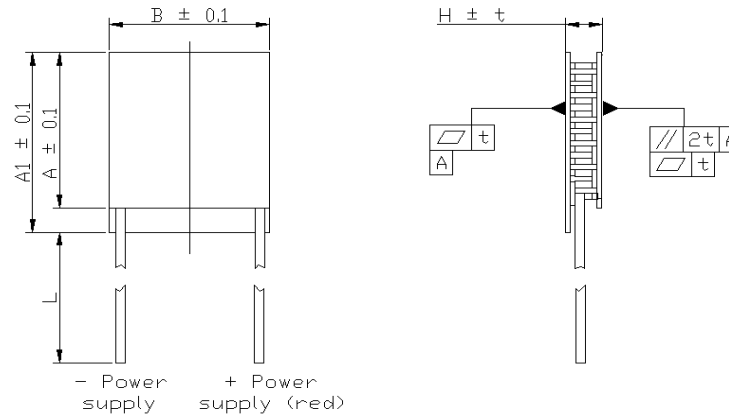
PO#

PO date

Thermoelectric module (TM) specification

PO position #	TM	Internal Solder Melting Temp, C	Max operating temperature, °C		Hot side temperature 25 °C				Rac at 25 °C		Ceramic size, mm		TM Height		Wire			Sealing
			short time	long time	I <sub>max</sub> , A	U <sub>max</sub> , V	Q <sub>max</sub> , W	dT <sub>max</sub> , K	Rac, Ohm	Tolerance ±, %	A/A1	B	Height, mm	Tolerance t, ± mm	S, AWG #	Length, mm	Tolerance ±, mm	
1	D-199-15-07-L2	138	130	115	14.9	25.3	233.2	70.0	1.30	10	49/49	49	3.80	0.02	18	100	5	
	ceramics: AlN version														PVC			
	lamel version														soldered on external labels (tabs)			

Clamping force: 54.0 - 108.1 kg



Max dT is reduced by 2-3K for silicon sealed and 1-2K for epoxy sealed versions.



### U(dT) at $T_{hot}=298K$

